

LNA IC for UHF Band (400 MHz to 800 MHz) Applications

FEATURES

- Low voltage operation +2.85 V typ.
- Low current consumption 3.0 mA typ. (High-Gain mode)  
0.1  $\mu$ A typ. (Low-Gain mode)
- High gain 14.5 dB typ. fRX = 620 MHz (High-Gain mode)
- Low noise figure 1.40 dB typ. fRX = 620 MHz (High-Gain mode)
- Low distortion -8.0 dBm typ. fRX = 620 MHz (High-Gain mode)  
(IIP3 +10 MHz offset)
- Small package 5 pin Plastic Small Surface Mount Package  
(SMINI Type)

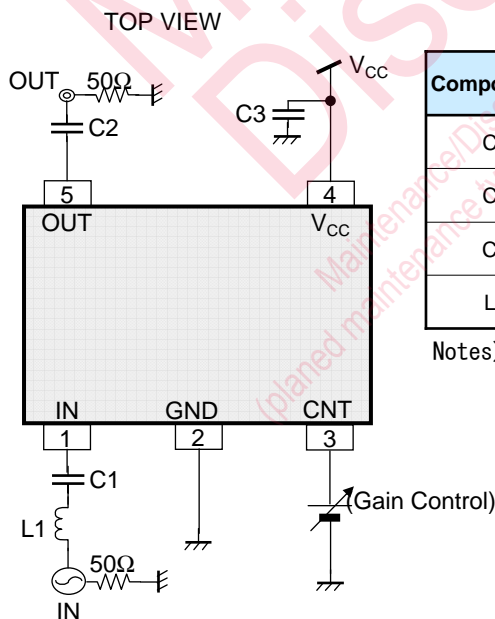
DESCRIPTION

AN26018A is LNA-IC for UHF Band (400 MHz to 800 MHz) Applications. Realizing high performance by using SiGe Bi-CMOS process ( $f_T = 90$  GHz,  $f_{max} = 140$  GHz). High/Low Gain-mode is changeable, controlled by integrated CMOS logic circuit. Achieving miniaturization by using small size package.

APPLICATIONS

- DTV (UHF)

SIMPLIFIED APPLICATION



Components	Size	Value	Part Number	Vendor
C1	0603	1 000 pF	GRM033B11C102KD01	Murata
C2	0603	1 000 pF	GRM033B11C102KD01	Murata
C3	0603	0.1 $\mu$ F	GRM033B30J104KE18	Murata
L1	0603	6.8 nH	LQP03T6N8H04	Murata

Notes) This application circuit is an example. The operation of mass production set is not guaranteed. You should perform enough evaluation and verification on the design of mass production set. You are fully responsible for the incorporation of the above application circuit and information in the design of your equipment.

## ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Rating	Unit	Note
Supply voltage	$V_{CC}$	3.6	V	*1
Supply current	$I_{CC}$	18	mA	—
Operating ambient temperature	$T_{opr}$	-20 to 70	°C	*2
Operating junction temperature	$T_j$	-40 to +125	°C	*2
Storage temperature	$T_{stg}$	-40 to +125	°C	*2
Input Voltage Range	IN (Pin No.1)	—	V	*3
	CNT (Pin No.3)	-0.3 to ( $V_{CC} + 0.3$ )	V	*4
	OUT (Pin No.5)	-0.3 to ( $V_{CC} + 0.3$ )	V	*4
ESD	HBM (Human Body Model)	2	kV	—
	MM (Machine Model)	100	V	—

Notes). This product may sustain permanent damage if subjected to conditions higher than the above stated absolute maximum rating. This rating is the maximum rating and device operating at this range is not guaranteeable as it is higher than our stated recommended operating range.

When subjected under the absolute maximum rating for a long time, the reliability of the product may be affected.

\*1: The values under the condition not exceeding the above absolute maximum ratings and the power dissipation.

\*2: Except for the power dissipation, operating ambient temperature, and storage temperature, all ratings are for  $T_a = 25^\circ\text{C}$ .

\*3: RF signal input pin. Do not apply DC current.

\*4: ( $V_{CC} + 0.3$ ) V must not be exceeded 3.6 V

## POWER DISSIPATION RATING

PACKAGE	$\theta_{JA}$	PD ( $T_a=25^\circ\text{C}$ )	PD ( $T_a=70^\circ\text{C}$ )
SSMINI-5DC	833.3°C/W	0.12W	0.06W

Note). For the actual usage, please refer to the PD- $T_a$  characteristics diagram in the package specification, supply voltage, load and ambient temperature conditions to ensure that there is enough margin follow the power and the thermal design does not exceed the allowable value.

**CAUTION**

Although this has limited built-in ESD protection circuit, but permanent damage may occur on it. Therefore, proper ESD precautions are recommended to avoid electrostatic damage to the MOS gates

## RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	Min.	Typ.	Max.	Unit	Note
Supply voltage range	$V_{CC}$	2.70	2.85	3.0	V	*1

Note) \*1 : The values under the condition not exceeding the above absolute maximum ratings and the power dissipation.

**ELECTRICAL CHARACTERISTICS**

Note)  $V_{cc} = 2.85\text{ V}$ ,  $T_a = 25^\circ\text{C} \pm 2^\circ\text{C}$  unless otherwise specified.

Parameter	Symbol	Condition	Limits			Unit	Note
			Min	Typ	Max		
<b>DC electrical characteristics</b>							
Supply current HG	IccH	Vcc current at High-Gain mode No input signal	—	3.0	4.0	mA	—
Supply current LG	IccL	Vcc current at Low-Gain mode No input signal	—	0.1	9.5	$\mu\text{A}$	—
Input voltage (High-Gain mode)	VIH	—	1.40	2.85	—	V	—
Input voltage (Low-Gain mode)	VIL	—	—	0.0	0.55	V	—
SW current (High)	IIH	Current at CNT pin $V_{IH} = V_{cc}$	—	11	40	$\mu\text{A}$	—

**ELECTRICAL CHARACTERISTICS (continued)**

Note)  $V_{cc} = 2.85\text{V}$ ,  $T_a = 25^\circ\text{C} \pm 2^\circ\text{C}$ ,  $f_{RX} = 620\text{ MHz}$ ,  $PRX = -30\text{ dBm}$ , CW unless otherwise specified.

Parameter	Symbol	Conditions	Limits			Unit	Note
			Min	Typ	Max		
<b>LNA AC electrical characteristics</b>							
Power Gain HG	GHS	High-Gain mode $f = f_{RX}$	12.5	14.5	16.5	dB	—
Power Gain LG	GLS	Low-Gain mode $f = f_{RX}$ , $PRX = -20\text{ dBm}$	-2.0	-1.5	—	dB	—
IIP3 +10 MHz offset	IIP31S	$f_1 = f_{RX} + 10\text{ MHz}$ $f_2 = f_{RX} + 20\text{ MHz}$ Input 2 signals ( $f_1$ , $f_2$ )	-14.5	-8.0	—	dBm	—

**APPLICATION INFORMATION**  
**REFERENCE VALUES FOR DESIGN**

Notes)  $V_{cc} = 2.85\text{ V}$

$T_a = 25^\circ\text{C} \pm 2^\circ\text{C}$ ,  $f_{RX} = 470\text{ MHz}, 620\text{ MHz}, 770\text{ MHz}$ ,  $PRX = -30\text{ dBm}$ , CW unless otherwise specified.

Parameter	Symbol	Conditions	Reference values			Unit	Note
			Min	Typ	Max		
<b>LNA AC electrical characteristics</b>							
Power Gain HG	GH	High-Gain mode $f = f_{RX}$	12.0	14.5	17.0	dB	*1
Power Gain LG	GL	Low-Gain mode $f = f_{RX}$ , $PRX = -20\text{ dBm}$	-2.5	-1.5	—	dB	*1
Noise Figure HG	NFH	High-Gain mode $f = f_{RX}$	—	1.5	1.9	dB	*1, *2
Noise Figure LG	NFL	Low-Gain mode $f = f_{RX}$	—	1.5	2.5	dB	*1
IIP3 +10 MHz offset HG	IIP3H1	High-Gain mode $f_1 = f_{RX} + 10\text{ MHz}$ $f_2 = f_{RX} + 20\text{ MHz}$ Input 2 signals ( $f_1, f_2$ )	-16.5	-8.0	—	dBm	*1
IIP3 -10 MHz offset HG	IIP3H2	High-Gain mode $f_1 = f_{RX} - 10\text{ MHz}$ $f_2 = f_{RX} - 20\text{ MHz}$ Input 2 signals ( $f_1, f_2$ )	-17.0	-8.5	—	dBm	*1
Input P1dB	IP1dBH	High-Gain mode $f = f_{RX}$	-11	-5	—	dBm	*1
Reverse Isolation HG	ISOH	High-Gain mode $f = f_{RX}$	—	-24	-18	dB	*1
Reverse Isolation LG	ISOL	Low-Gain mode $f = f_{RX}$	—	-1.6	-1.0	dB	*1
Input Return Loss HG	S11H	High-Gain mode $f = f_{RX}$	5.0	9.5	—	dB	*1
Input Return Loss LG	S11L	Low-Gain mode $f = f_{RX}$	12	20	—	dB	*1
Output Return Loss HG	S22H	High-Gain mode $f = f_{RX}$	7	23	—	dB	*1
Output Return Loss LG	S22L	Low-Gain mode $f = f_{RX}$	10	12	—	dB	*1
K-Factor	KH	High-Gain mode $f = 300\text{ kHz to }6\text{ GHz}$	1.0	1.5	—	—	*1
Switching Time	TSW	High-Gain mode → Low-Gain mode Low-Gain mode → High-Gain mode	—	3.2	10.0	us	*1

Note) \*1 : Checked by design, not production tested.  
\*2 : Connector & substrate loss (0.10 dB) included.

**APPLICATION INFORMATION (continued)**  
**REFERENCE VALUES FOR DESIGN (continued)**

Notes)  $V_{cc} = 2.7\text{ V to }3.0\text{ V}$

All characteristics are specified under  $T_a = -20^{\circ}\text{C to }70^{\circ}\text{C}$

Parameter	Symbol	Conditions	Reference values			Unit	Note
			Min	Typ	Max		
<b>DC electrical characteristics</b>							
Supply current HG	IccHT	$V_{cc}$ current at High-Gain mode No input signal	—	3.0	4.5	mA	*1
Supply current LG	IccLT	$V_{cc}$ current at Low-Gain mode No input signal	—	0.1	10	$\mu\text{A}$	*1
Input voltage (High-Gain mode)	VIHT	—	1.50	2.85	—	V	*1
Input voltage (Low-Gain mode)	VILT	—	—	0.0	0.40	V	*1
SW current (High)	IIHT	Current at CNT pin $V_{IH} = V_{cc}$	—	11	50	$\mu\text{A}$	*1

Note) \*1 : Checked by design, not production tested.

**APPLICATION INFORMATION (continued)**

**REFERENCE VALUES FOR DESIGN (continued)**

Notes)  $V_{cc} = 2.7\text{ V to }3.0\text{ V}$

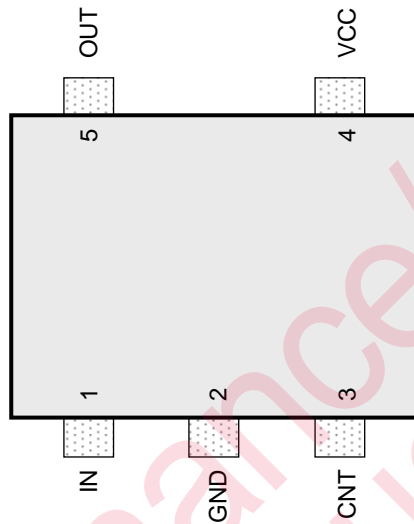
All characteristics are specified under  $T_a = -20^\circ\text{C to }70^\circ\text{C}$ ,  $f_{RX} = 470\text{ MHz, }620\text{ MHz, }770\text{ MHz}$ ,  
 $PRX = -30\text{ dBm, CW}$

Parameter	Symbol	Conditions	Reference values			Unit	Note
			Min	Typ	Max		
<b>LNA AC electrical characteristics</b>							
Power Gain HG	GHT	High-Gain mode $f = f_{RX}$	11.5	14.5	17.5	dB	*1
Power Gain LG	GLT	Low-Gain mode $f = f_{RX}, PRX = -20\text{ dBm}$	-2.7	-1.5	—	dB	*1
Noise Figure HG	NFHT	High-Gain mode $f = f_{RX}$	—	1.5	2.3	dB	*1, *2
Noise Figure LG	NFLT	Low-Gain mode $f = f_{RX}$	—	1.5	2.7	dB	*1
IIP3 +10 MHz offset HG	IIP3H1T	High-Gain mode $f_1 = f_{RX} + 10\text{ MHz}$ $f_2 = f_{RX} + 20\text{ MHz}$ Input 2 signals ( $f_1, f_2$ )	-17.0	-8.0	—	dBm	*1
IIP3 -10 MHz offset HG	IIP3H2T	High-Gain mode $f_1 = f_{RX} - 10\text{ MHz}$ $f_2 = f_{RX} - 20\text{ MHz}$ Input 2 signals ( $f_1, f_2$ )	-17.5	-8.5	—	dBm	*1
Input P1dB HG	IP1dBHT	High-Gain mode $f = f_{RX}$	-13	-5	—	dBm	*1
K-Factor	KHT	High-Gain mode $f = 300\text{ kHz to }6\text{ GHz}$	1.0	1.5	—	—	*1
Switching Time	TSWT	High-Gain mode $\rightarrow$ Low-Gain mode Low-Gain mode $\rightarrow$ High-Gain mode	—	3.2	10.0	$\mu\text{s}$	*1

Note) \*1 : Checked by design, not production tested.  
 \*2 : Connector & substrate loss (0.10 dB) included.

**PIN CONFIGURATION**

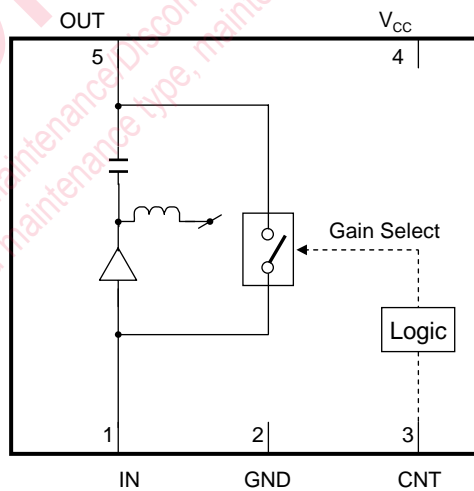
Top View



**PIN FUNCTIONS**

Pin No.	Pin name	Type	Description
1	IN	Input	RF Input
2	GND	Ground	GND
3	CNT	Input	High-Gain / Low-Gain switch L: Low-Gain Mode H: High-Gain Mode
4	VCC	Power Supply	V <sub>CC</sub>
5	OUT	Output	RF Output

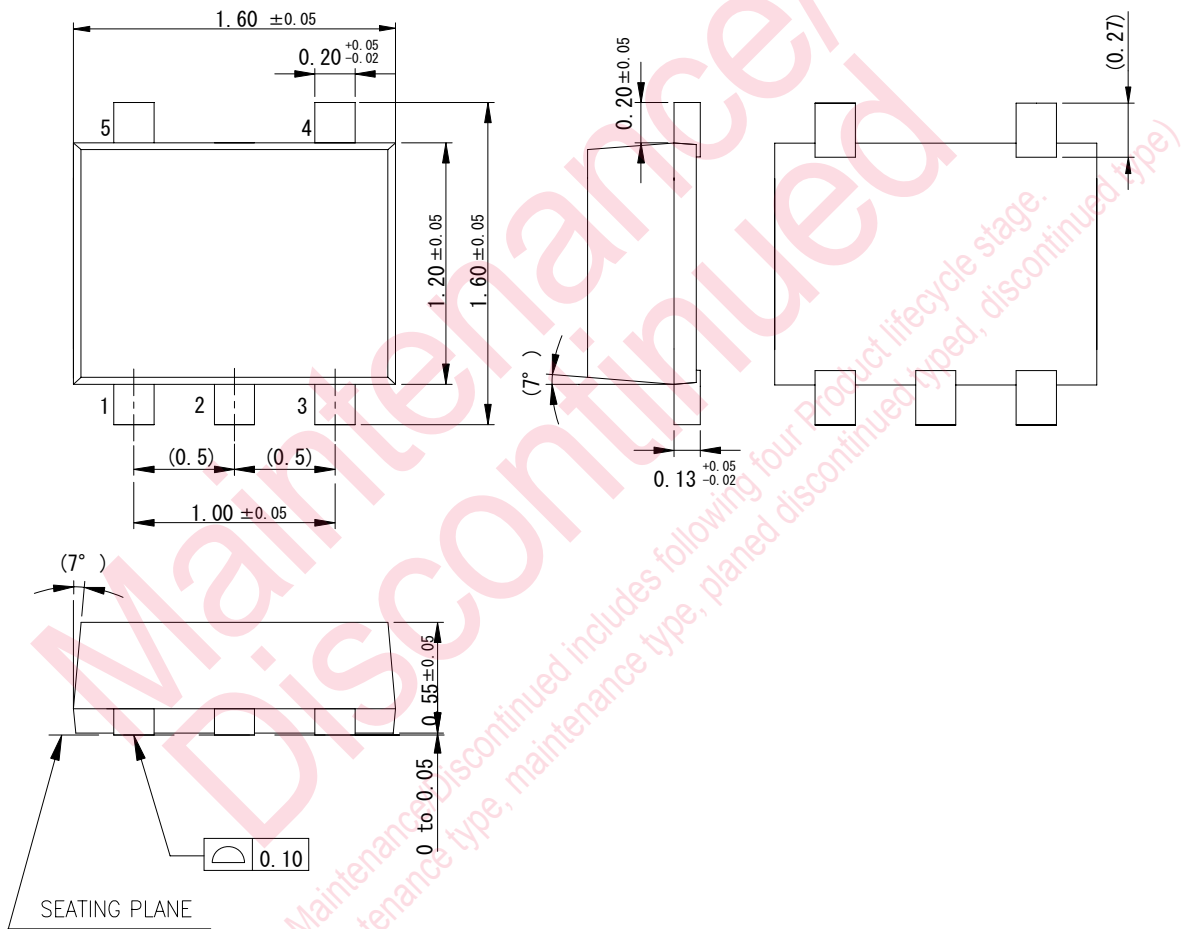
**FUNCTIONAL BLOCK DIAGRAM**



**PACKAGE INFORMATION ( Reference Data )**

Package Code:SSMINI-5DC

Unit:mm



Body Material	: Br / Sb Free Epoxy Resin
Lead Material	: Cu Alloy
Lead Finish Method	: SnBi Plating



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3. Pay attention to the direction of LSI. When mounting it in the wrong direction onto the PCB (printed-circuit-board), it might smoke or ignite.
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5. Perform a visual inspection on the PCB before applying power, otherwise damage might happen due to problems such as a solder-bridge between the pins of the semiconductor device. Also, perform a full technical verification on the assembly quality, because the same damage possibly can happen due to conductive substances, such as solder ball, that adhere to the LSI during transportation.
6. Take notice in the use of this product that it might break or occasionally smoke when an abnormal state occurs such as output pin-VCC short (Power supply fault), output pin-GND short (Ground fault), or output-to-output-pin short (load short) .

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